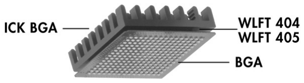
Data sheet Product ICK BGA 29 x 29 x 14

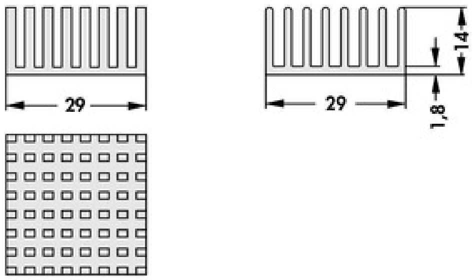


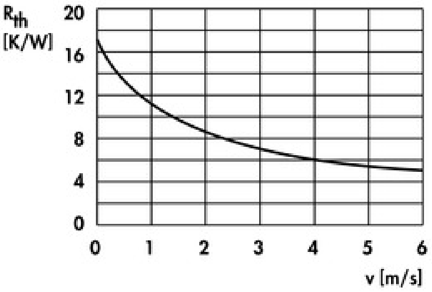
Heatsinks and active heatsinks for processors>Heatsinks for BGAs
29 x 29 x 14 mm, for IC design BGA and others

Features

way of fixation:	**therm. conductive foil** **therm. cond. adhesive**
socket:	**universal**
suitable for processor type:	**universal**
width:	**29 mm**
height:	**14 mm**
plate thickness:	**1.8 mm**
length:	**29 mm**
thermal resistance:	**17 - 5 K/W**
dissipation loss:	**3.5 W**
surface:	**black anodised**

Technical Drawing





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